## L810HW SERIES

## 1. PART NO. EXPRESSION :

L 8 1 0 H W - 1 R 0 M F -					
(a)	(b)	(C)	(d)(e)	(f)	

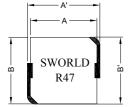
(a) Series	code
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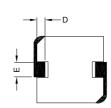
- (b) Type code
- (c) Inductance code : 1R0 = 1.0uH
- (d) Tolerance code :  $M = \pm 20\%$

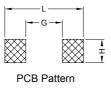
(f) 11 ~ 99 : Internal controlled number

(e) F : RoHS Compliant

### 2. CONFIGURATION & DIMENSIONS :







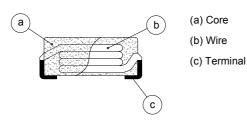
Unit:m/m

A'	A	В'	В	C'	С	D	E	G	н	L
13.9 Max	. 12.7±0.3	13.5 Max.	12.7±0.3	3.7 Max.	3.5 Max.	2.5±0.5	3.0±0.5	7.0 Ref.	4.5 Ref.	15.0 Ref.

## 3. SCHEMATIC :



## 4. MATERIALS :



## 5. FEATURES :

a) Shielded Construction

b) Frequency up to 5MHz



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## 6. GENERAL SPECIFICATION :

a) Test Freq. : Q : 100KHz/1.0V

b) Ambient Temp. : 20°C

c) Operating Temp. : -55°C to +125°C

d) Storage Temp. : -55°C to +125°C

e) Humidity Range : 50 ~ 60% RH

f) Heat Rated Current (Irms) : Will cause the coil temp. rise approximately  $\Delta T$ =40°C without core loss.

g) Saturation Current (Isat) : Will cause Lo to drop approximately 20% typ.

h) Part Temperature (Ambient+Temp. Rise) : Should not exceed 125°C under worst case operating conditions.

### 7. ELECTRICAL CHARACTERISTICS :

Part No.	Inductance L₀ (μH) ±20% @ 0 Adc	Test Frequency (Hz)	Irms ( A ) Typ.	Isat ( A ) Typ.	DCR ( mΩ ) Max.	Q Min.
L810HW-R47MF-	0.47	1.0V/100K	32	44	2.0	12
L810HW-R68MF-	0.68	1.0V/100K	28	40	2.5	12
L810HW-R82MF-	0.82	0.25V/100K	25	38	3.0	-
L810HW-1R0MF-	1.00	1.0V/100K	24	36	3.5	20
L810HW-1R5MF-	1.50	1.0V/100K	19	28	5.5	20
L810HW-2R2MF-	2.20	1.0V/100K	16	20	8.0	20
L810HW-3R3MF-	3.30	1.0V/100K	12	18	12	20
L810HW-4R7MF-	4.70	1.0V/100K	10	16	15	20
L810HW-6R8MF-	6.80	1.0V/100K	9	13	22	20
L810HW-100MF-	10.0	1.0V/100K	7	9.5	34	20

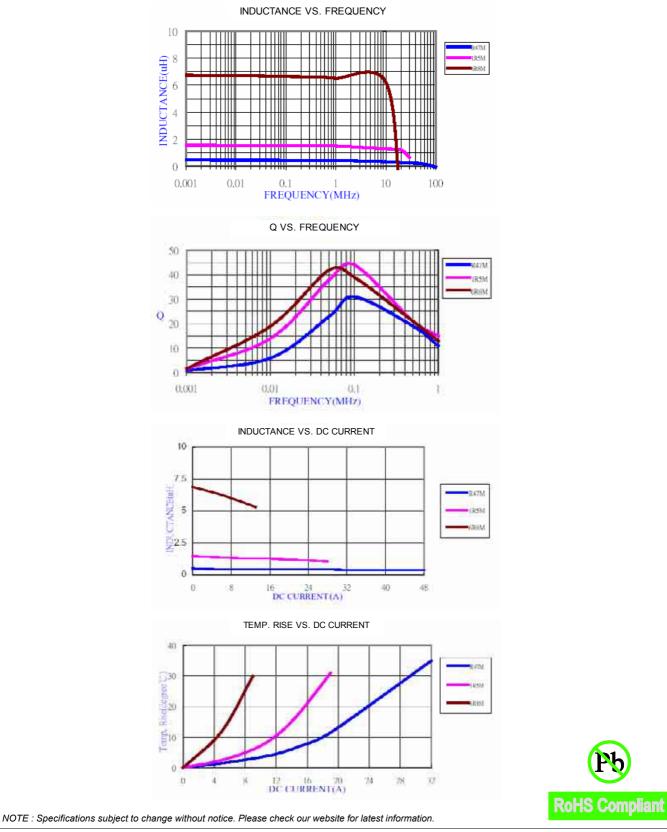


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## 8. CHARACTERISTICS CURVES :



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TEMP. RISE(°C) 

TEMP. RISE (°C)

## 8. CHARACTERISTICS CURVES :

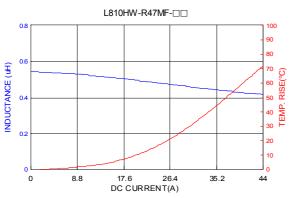
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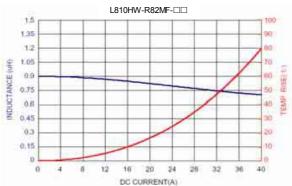
1.8

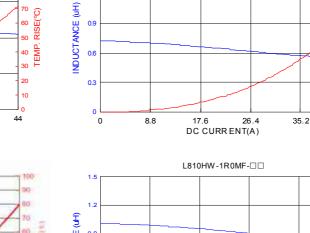
1.2

0.6

INDUCTANCE (uH)

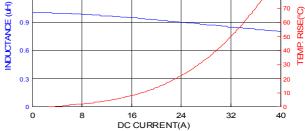




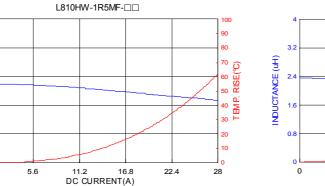


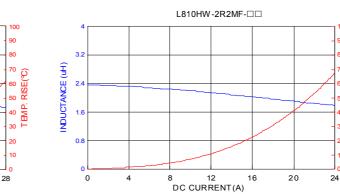
1.5

1.2



L810HW-R68MF-





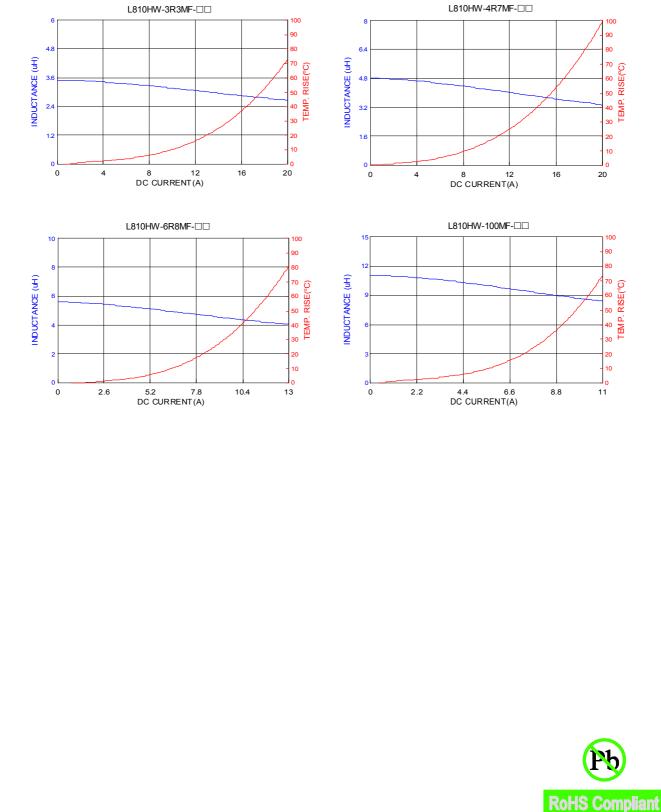


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8. CHARACTERISTICS CURVES :

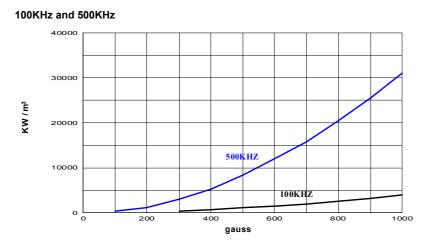
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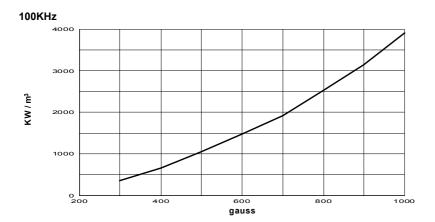
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## 9. CORE LOSS :



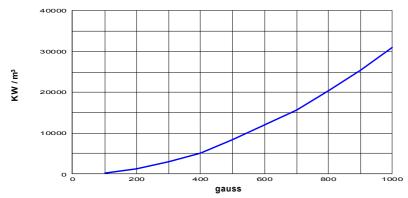
material gauss loss	100KHz	500KHz
100	-	266
200	-	1,234
300	351.7	2,932
400	665.9	5,195
500	1,039	8,336
600	1,471	12,025
700	1,923	15,715
800	2,537	20,444
900	3,148	25,429
1000	3,902	31,002

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500KHz



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## L810HW SERIES

#### PERFORMANCE TEST CONDITION ITEM **Electrical Characteristics Test** HP4284A, CH11025, CH3302, CH1320, CH1320S Inductance Refer to standard electrical characteristics list LCR meter. DCR CH16502, Agilent33420A Micro-Ohm Meter. Heat Rated Current (Irms) Irms(A) will cause the coil temperature rise approximately $\Delta T=40^{\circ}C$ without core loss 1. Applied the allowed DC current 2. Temperature measured by digital surface thermometer Saturation Current (Isat) Isat(A) will cause Lo to drop approximately 20% Mechanical Performance Test Solderability Test More than 90% of the terminal electrode Preheat : 150°C, 60sec. should be covered with solder. Solder : Sn99.95-Cu0.05 Solder Temperature : 245±5°C Preheating Dipping Natural Flux for lead free : rosin 245°C cooling Dip Time : 4±1sec. 150°C 60 4+1 seconds conds Solder Heat Resistance 1. Appearance : No significant abnormality Preheat : 150°C, 60sec. 2. Inductance change : Within ±20% Solder : Sn99.95-Cu0.05 Solder Temperature : 260±5°C Preheating Dipping Natural Flux for lead free : rosin cooling 260°C Dip Time : 10±0.5sec. 150°C 60 10±0.5 Reliability Test High Temperature Temperature : 125±5°C Life Test Time : 500±12 hours Measure at room temperature after placing for 2 to 3 hrs. Low Temperature Temperature : -55±5°C Life Test 1. Appearance : No damage Time : 500±12 hours Measure at room temperature after placing for 2 to 3 hrs. 2. Inductance : Within ±20% of initial value. Thermal Shock No disconnection or short circuit. Conditions of 1 cycle. Step Temperature (°C) Times (min.) -55±3 1 30±3 2 Room Temperature Within 3 3 $+125 \pm 3$ $30 \pm 3$ 4 Room Temperature Within 3 Total : 5 cycles Measure at room temperature after placing for 2 to 3 hrs. Humidity Resistance 1. Appearance : No damage Temperature : 40±5°C Humidity : 90% to 95% 2. Inductance : Within ±20% of initial value. Applied Current : Rated Current No disconnection or short circuit. Time : 500±12 hours Measure at room temperature after placing for 2 to 3 hrs. Frequency : 10-55-10Hz for 1 min. Random Vibration Test Appearance : Cracking, shipping and any other Amplitude : 1.52mm defects harmful to the characteristics should not Directions & times : X, Y, Z directions for 2 hours. be allowed. A period of 2 hours in each of 3 mutually perpendicular directions (Total 6 hours).

### **10. RELIABILITY AND TEST CONDITION :**

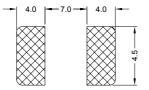
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### **11. SOLDERING AND MOUNTING :**

### 11-1. Recommended PC Board Pattern



### 11-2. Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. Our terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

### 11-2.1 Solder Re-flow :

Recommended temperature profiles for re-flow soldering in Figure 1.

### 11-2.2 Soldering Iron (Figure 2) :

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended. Note :

- .
- a) Preheat circuit and products to 150°C.
- b) 280°C tip temperature (max)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (max)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 3 secs.

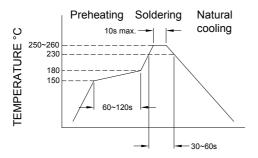


Figure 1. Re-flow Soldering

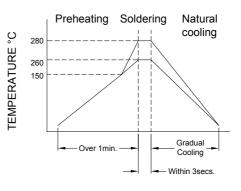


Figure 2. Iron Soldering



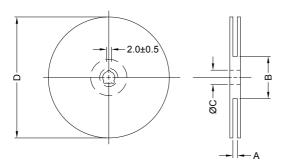
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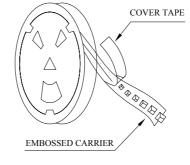
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## 12. PACKAGING INFORMATION :

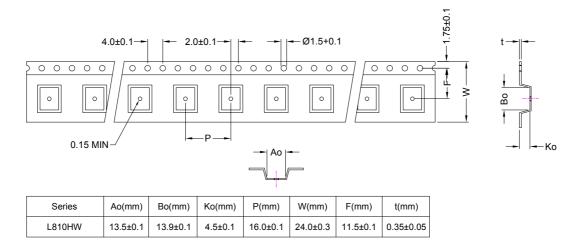
## 12-1. Reel Dimension





Туре	A(mm)	B(mm)	C(mm)	D(mm)
13" x 24mm	24.0±0.5	100±2.0	13.5±0.5	330

## 12-2 Tape Dimension



### 12-3. Packaging Quantity

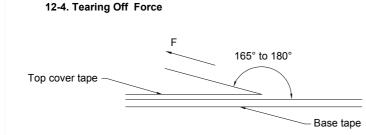
Size	L810HW
Chip / Reel	600
Inner Box	1200
Carton	4800



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The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(°C)	(%)	(hPa)	(mm/min)
5~35	45~85	860~1060	

## **Application Notice**

- 1. Storage Conditions :
  - To maintain the solderabililty of terminal electrodes :
    - a) Temperature and humidity conditions : Less than 30°C and 70% RH.
    - b) Recommended products should be used within 6 months from the time of delivery.
    - c) The packaging material should be kept where no chlorine or sulfur exists in the air.

### 2. Transportation :

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) The use of tweezers or vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.



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